



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Koos et al.

Attorney Docket No.:  
NOVLP068/NVLS-2818

Application No.: 10/690,084

Examiner: Vinh, Lan

Filed: October 20, 2003

Group: 1765

Title: METHOD FOR FABRICATION OF  
SEMICONDUCTOR INTERCONNECT  
STRUCTURE WITH REDUCED CAPACITANCE,  
LEAKAGE CURRENT, AND IMPROVED  
BREAKDOWN VOLTAGE

Confirmation No.: 4873

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on June 1, 2007 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: \_\_\_\_\_

Tara Hayden

**INFORMATION DISCLOSURE STATEMENT  
37 CFR §§1.56 AND 1.97(b)**

Mail Stop RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:


The reference(s) identified in the attached PTO Form 1449 (copies of non-U.S. references are attached) may be material to examination of the above-identified patent application. Applicants identify these reference(s) in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make the identified reference(s) of official record in this application.


This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that the identified reference(s) indeed constitute prior art.

This Information Disclosure Statement is: (i) filed within three (3) months of the filing date of the above-referenced application, (ii) believed to be filed before the mailing date of a first Office Action on the merits, or (iii) believed to be filed before the mailing of a first Office Action after the filing of a Request for Continued Examination under §1.114. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure

Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. NOVLP068 ).

Respectfully submitted,  
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<b>Form 1449 (Modified)</b> <b>Information Disclosure</b> <b>Statement By Applicant</b>  (Use Several Sheets if Necessary)	<b>Atty Docket No.</b>	NOVLP068/NVLS-2818
	<b>Application No.:</b>	10/690,084
	<b>Applicant</b>	Koos et al.
	<b>Filing Date</b>	October 20, 2003
	<b>Group</b>	1765
		Page 1 of 1

#### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	1.	7,056,648	06.2006	Cooper et al.			
	2.	4,181,760	01.1980	Feldstein, Nathan			
	3.	2002/0084529	07.2002	Dubin et al.			

#### Foreign Patent or Published Foreign Patent Application

Examiner Initial		Document No.	Publication Date	Country or Patent Office	Class	Sub-Class	Translation	
							Yes	No
	4.	JP02111883	04.1990	JPO				

#### Other Documents

Examiner Initial	No.	Author, Title, Place (e.g. Journal) of Publication, Date
	5.	Mayer et al., "Pad-Assisted Electropolishing," Novellus Systems, Inc., Appln No.: 11/213,190, filed August 26, 2005. [NVLS-3037]
	6.	Mayer et al., "Topography Reduction and Control by Selective Accelerator Removal," Novellus Systems, Inc., Appln. No.: 11/602,128, filed November 20, 2006. [NVLS-2960]
	7.	Aksu et al., "The Role of Glycine in the Chemical Mechanical Planarization of Copper," Journal of The Electrochemical Society, 149 (6) G352-G361 (200), Department of Materials Science and Engineering, University of California, Berkeley, Berkeley, California 94720-1760, USA
	8.	U.S. Office Action mailed August 16, 2006 from U.S. Application No. 10/742,006. [NOVLP065/NVLS-2796]

<b>Examiner</b>	<b>Date Considered</b>
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Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.